ON Semiconductor				10/15/2019
Base Part		MOC211M		Pb-free
Orderable Part		MOC211M	Total weight (mg)	168.58636
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Coupling Gel	4.18236	Dimethyl Cyclosiloxanes	69430-24-6	1.0989011
		Trimethoxy(methyl)silane (C4H12O3Si)	1185-55-3	98.9010989
Die	4.043	Gallium Arsenide (AsGa)	1303-00-0	6.99975266
		Silicon (Si)	7440-21-3	93.00024734
Die Attach	0.754	Silver (Ag)	7440-22-4	80
		Phenolic Resin-2	54208-63-8	20
Lead Frame	59.197	Silver (Ag)	7440-22-4	0.25001267
		Zinc (Zn)	7440-66-6	0.11993851
		Iron (Fe)	7439-89-6	2.29741372
		Copper (Cu)	7440-50-8	97.30222815
		Phosphorus (P)	7723-14-0	0.03040695
Mold Compound-White	98.06	2,6-dibromo-4-[1-(3-bromo-4-hydroxyphenyl)-1-methylethyl]phenol	6386-73-8	3.9975526
		Ortho Cresol Novolac Resin	29690-82-2	23.96492
		Antimony Trioxide (Sb2O3)	1309-64-4	2.9981644
		Fused Silica (SiO2)	60676-86-0	69.03936
Plating	2.1	Tin (Sn)	7440-31-5	100
Wire Bond - Au	0.25	Gold (Au)	7440-57-5	100

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:

http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF